FEATURES

Avalanche Rugged Technology

Rugged Gate Oxide Technology

Lower Input Capacitance

Improved Gate Charge

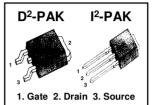
• Extended Safe Operating Area

● 175°C Operating Temperature

• Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 100V$

• Lower $R_{DS(ON)}$: 0.041 Ω (Typ.)

 $BV_{DSS} = 100 V$ $R_{DS(on)} = 0.052 Ω$ $I_D = 28 A$



Absolute Maximum Ratings

| Symbol | Characteristic | Value | Units | |
|-------------------|---|--------------|-------|--|
| $V_{	extsf{DSS}}$ | Drain-to-Source Voltage | 100 | V | |
| | Continuous Drain Current (T _C =25°C) | 28 | — A | |
| I _D | Continuous Drain Current (T _C =100℃) | 19.8 | | |
| I _{DM} | Drain Current-Pulsed ① | 110 | Α | |
| V_{GS} | Gate-to-Source Voltage | ±20 | V | |
| E _{AS} | Single Pulsed Avalanche Energy ② | 523 | mJ | |
| I _{AR} | Avalanche Current ① | 28 | Α | |
| E _{AR} | Repetitive Avalanche Energy ① | 10.7 | mJ | |
| dv/dt | Peak Diode Recovery dv/dt 3 | 6.5 | V/ns | |
| | Total Power Dissipation $(T_A=25^{\circ}C)^*$ | 3.8 | W | |
| P_{D} | Total Power Dissipation (T _C =25°C) | 107 | W | |
| | Linear Derating Factor | 0.71 | W/℃ | |
| | Operating Junction and | FF +- 47F | | |
| $T_J \ , T_STG$ | Storage Temperature Range | - 55 to +175 | | |
| т | Maximum Lead Temp. for Soldering | 200 | °C | |
| T _L | Purposes, 1/8? from case for 5-seconds | 300 | | |

Thermal Resistance

| Symbol | Characteristic | Тур. | Max. | Units |
|-------------------------------------|-----------------------|------|------|-------|
| $R_{\scriptscriptstyle{\Theta JC}}$ | Junction-to-Case | | 1.4 | |
| $R_{\scriptscriptstyle{\ThetaJA}}$ | Junction-to-Ambient * | | 40 | °C/W |
| $R_{\scriptscriptstyle{\ThetaJA}}$ | Junction-to-Ambient | | 62.5 | |

^{*} When mounted on the minimum pad size recommended (PCB Mount).



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Electrical Characteristics (T_C =25 $^{\circ}$ C unless otherwise specified)

| Symbol | Characteristic | Min. | Тур. | Max. | Units | Test Condition | |
|-----------------------------------|---|------|-------|-------|------------|----------------------------------|--|
| BV _{DSS} | Drain-Source Breakdown Voltage | 100 | | | ٧ | $V_{GS}=0V,I_{D}=250\mu A$ | |
| Δ BV/ Δ T $_{ m J}$ | Breakdown Voltage Temp. Coeff. | | 0.11 | | V/°C | I _D =250μA | |
| $V_{GS(th)}$ | Gate Threshold Voltage | 2.0 | | 4.0 | ٧ | $V_{DS} = 5V, I_{D} = 250 \mu A$ | |
| | Gate-Source Leakage, Forward | | | 100 | nA | V _{GS} =20V | |
| I _{GSS} | Gate-Source Leakage, Reverse | | | -100 | IIA | V _{GS} =-20V | |
| , | Dunin to Course Lookens Cumant | | | 10 | | V _{DS} =100V | |
| I _{DSS} | Drain-to-Source Leakage Current | | | 100 | μ A | $V_{DS}=80V, T_{C}=150$ °C | |
| R _{DS(on)} | Static Drain-Source On-State Resistance | | | 0.052 | Ω | $V_{GS} = 10V, I_D = 14A$ 4 | |
| g _{FS} | Forward Transconductance | | 22.56 | | S | V_{DS} =40V, I_D =14A (4) | |
| C _{iss} | Input Capacitance | | 1320 | 1710 | | \/ | |
| C _{oss} | Output Capacitance | | 325 | 380 | рF | $V_{GS}=0V, V_{DS}=25V, f=1MHz$ | |
| C _{rss} | Reverse Transfer Capacitance | | 148 | 170 | | See Fig 5 | |
| t _{d(on)} | Turn-On Delay Time | | 18 | 50 | | V 50V L 00A | |
| t _r | Rise Time | | 18 | 50 | | $V_{DD} = 50 V, I_{D} = 28 A,$ | |
| $t_{d(off)}$ | Turn-Off Delay Time | | 90 | 180 | ns | $R_{G}=9.1\Omega$ | |
| t _f | Fall Time | | 56 | 120 | | See Fig 13 4 5 | |
| Q_g | Total Gate Charge | | 60 | 78 | | $V_{DS} = 80V, V_{GS} = 10V,$ | |
| Q_gs | Gate-Source Charge | | 10.8 | | nC | I _D =28A | |
| Q_{gd} | Gate-Drain(獃iller? Charge | | 27.9 | | | See Fig 6 & Fig 12 4 5 | |

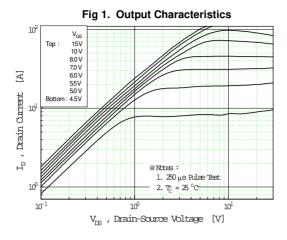
Source-Drain Diode Ratings and Characteristics

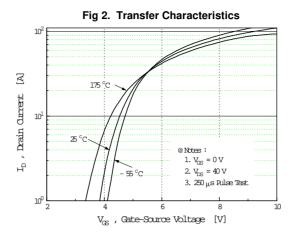
| Symbol | Characteristic | Min. | Тур. | Max. | Units | Test Condition |
|-----------------|---------------------------|------|------|------|-------|---|
| I _S | Continuous Source Current | | | 28 | ^ | Integral reverse pn-diode |
| I _{SM} | Pulsed-Source Current ① | | | 110 | Α | in the MOSFET |
| V_{SD} | Diode Forward Voltage 4 | | | 1.5 | ٧ | T _J =25 °C,I _S =28A,V _{GS} =0V |
| t _{rr} | Reverse Recovery Time | | 132 | | ns | T _J =25 °C ,I _F =28A |
| Q_{rr} | Reverse Recovery Charge | | 0.63 | | μC | di _F /dt=100A/µs 4 |

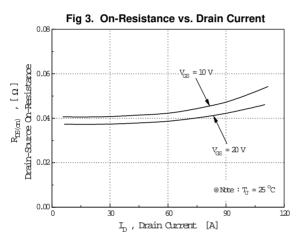
Notes;

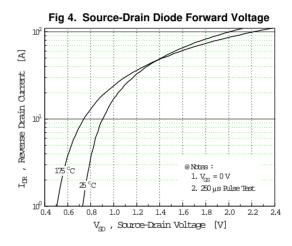
- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② L=1mH, I $_{AS}$ =28A, V $_{DD}$ =25V, R $_{G}$ =27 Ω , Starting T $_{J}$ =25 $^{\circ}$ C
- $\begin{tabular}{ll} \hline (3) & I_{SD} \le 28A, \ di/dt \le 400A/\mu s, \ V_{DD} \le BV_{DSS} \,, \ Starting \ T_J = 25\,^\circ\!\! C \\ \hline \end{tabular}$
- ④ Pulse Test : Pulse Width = 250µs, Duty Cycle ≤ 2%
- 5 Essentially Independent of Operating Temperature

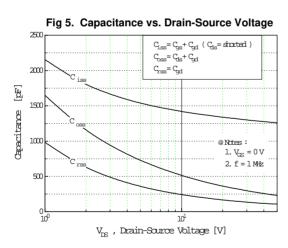


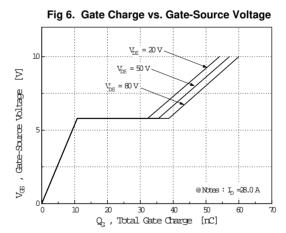




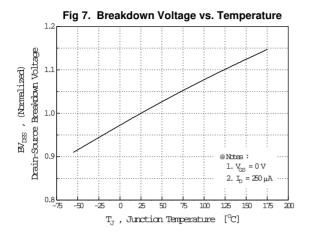


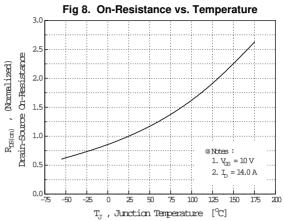


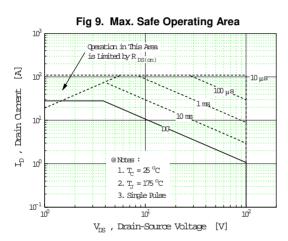


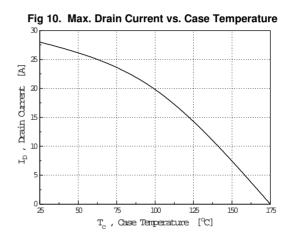












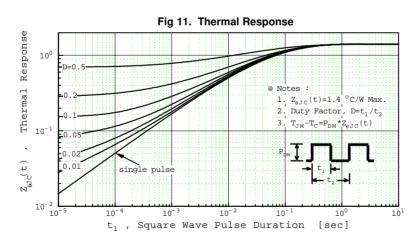




Fig 12. Gate Charge Test Circuit & Waveform

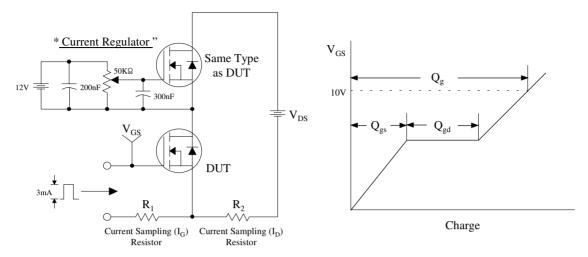


Fig 13. Resistive Switching Test Circuit & Waveforms

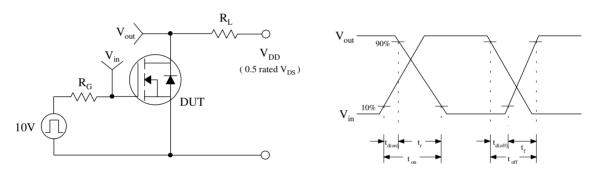


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

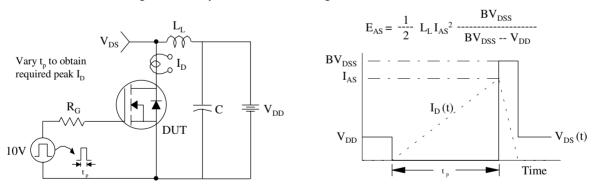
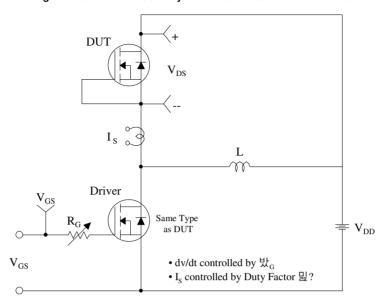
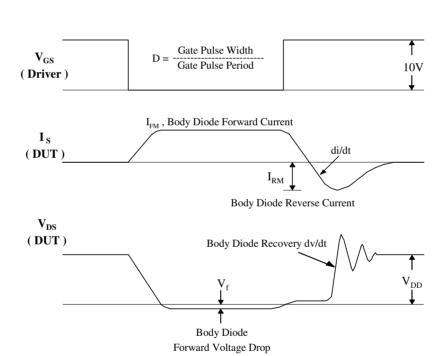




Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms







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